60V,150mA,2.1uA,High PSRR,High Voltage,Low-Dropout Voltage Regulator

Features

- Low quiescent current: 2.1uA
- Wide input voltage range: 5V to 60V
- High output current: 150mA
- High PSRR: 70dB at 1kHz
- Low dropout voltage: 650mV at 100mA
- Output voltage tolerance: ±1%/±2%
- Fast transient response
- Current limit protection
- Short circuit protection
- Thermal shutdown protection
- Available packages：SOT23-3, SOT89-3, SOT23-5 and TO252-3
- Fixed output voltages: 3.0V, 3.3V, 3.6V ,5.0V and 12.0V

Applications

- Battery-powered equipment
- Micro controller applications
- Home appliance

Description

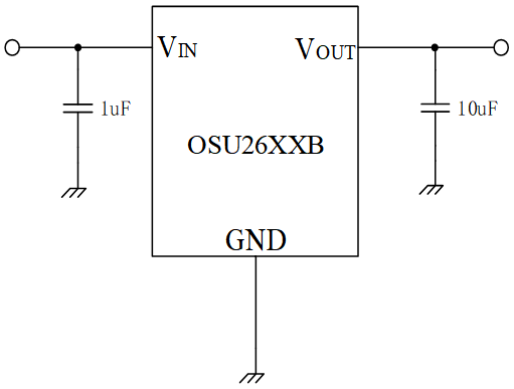
The OSU26XXA/B series is an ultra-small, low dropout (LDO) linear regulator that can source 150mA of output current. The OSU26XXA/B series is designed to provide high PSRR, high input voltage, and excellent load and line transient performance.

The OSU26XXA/B series has thermal shutdown, current limit, and short Circuit protections for added safety.

The OSU26XXA/B series contains five fixed output voltages of 3.0V, 3.3V,3.6V,5.0V and 12.0V.

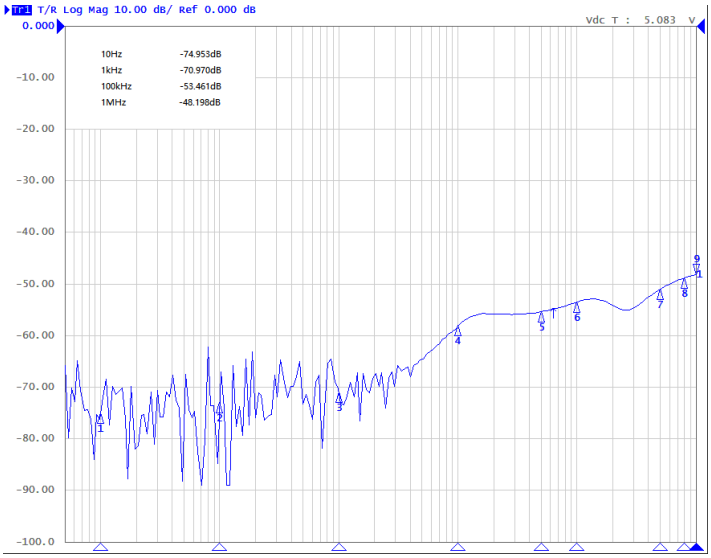
PART NUMBER	PACKAGE	BODY SIZE(NOM)
OSU26XXA/BTE	SOT23-3	2.9mm*2.8mm
OSU26XXA/BTS-DAF	SOT89-3	4.5mm*4.2mm
OSU26XXA/BTG	SOT23-5	2.9mm*2.8mm
OSU26XXA/BTQ	TO252-3	6.5mm*10.0mm

Typical Application



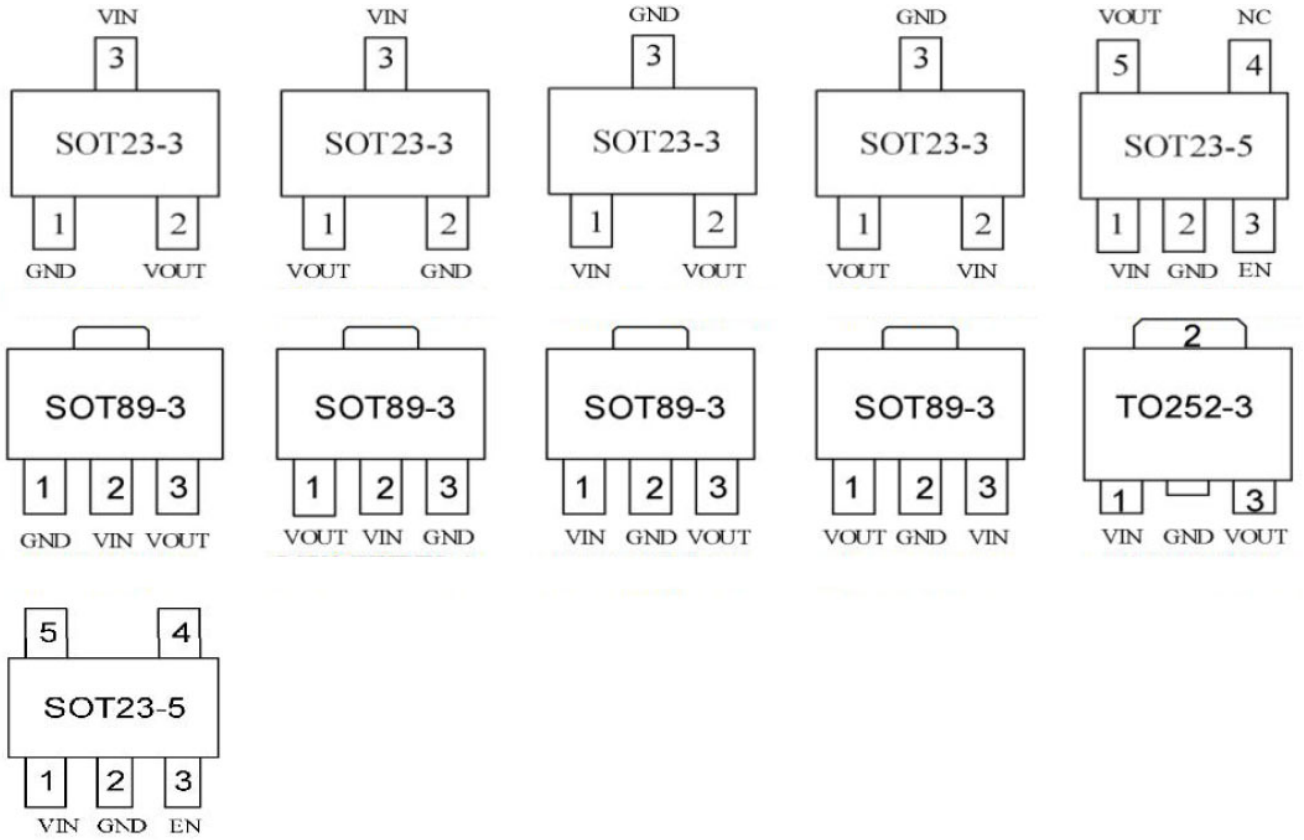
60V, Low-Dropout Voltage Regulator

PSRR



V_{IN}=7V,V_{OUT}=5V,I_{OUT}=10mA

Pin Configuration and Functions



Name	SOT23-3				Description
	OSU26XXA/BTE	OSU26XXA/BTE-A	OSU26XXA/BTE-B	OSU26XXA/BTE-C	
GND	1	2	3	3	Ground pin
VOUT	2	1	2	1	Output pin
VIN	3	3	1	2	Input pin
Name	**SOT89-3**				**Description**
	OSU26XXA/BTS	OSU26XXA/BTS-A	OSU26XXA/BTS-B	OSU26XXA/BTS-C	
GND	1	3	2	2	Ground pin
VOUT	3	1	3	1	Output pin
VIN	2	2	1	3	Input pin
Name	**SOT23-5**		**TO252-3**		**Description**
	OSU26XXA/BTG-A		OSU26XXA/BTQ		
VIN	1		1		Input pin
GND	2		2		Ground pin
EN	3				Enable pin
NC	4				No connection
VOUT	5		3		output Pin

Absolute Maximum Ratings

Parameter	Description	Min	Max	Unit
Input voltage	VIN to GND	-0.3	80	V
	VOUT to GND	-0.3	12	V
	VIN to VOUT	-0.3	75	V
Current	Peak output current	Internally limited		
Temperature	Operating temperature range	-40	125	℃
	Storage temperature	-40	150	℃
Thermal resistance (Junction to ambient)	SOT89-3	130		℃/W
	SOT23-3	200		℃/W
	SOT23-5	200		℃/W
	TO252-3	80		℃/W
Power dissipation	SOT89-3	900		mW
	SOT23-3	600		mW
	SOT23-5	600		mW
	TO252-3	1700		mW

Note:

exceeding the range specified by the rated parameters will cause damage to the chip, and the working state of the chip beyond the range of rated parameters cannot be guaranteed. Exposure outside the rated parameter range will affect the reliability of the chip.

ESD Ratings

Parameter	Description	Range	Unit
V_{ESD}	Human body model(HBM)	4	KV

Note:

JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

Electrical Characteristics

(At T_A=25℃, C_{IN}=1uF, V_{IN}=V_{OUTNOM}+1.0V, C_{OUT}=10uF, unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V_{IN}	Operating input voltage		5	—	60	V
I_{GND}	Quiescent current	V_{IN}=12V, No load	1.9	2.1	2.3	uA
V_{OUT}	Output voltage	V_{IN}=12V, I_{OUT}=10mA	V_{OUTNOM} * 0.98	V_{OUTNOM}	V_{OUTNOM} * 1.02	V
I_{OUT_MAX}	Output current		150	—	—	mA
V_{DROP}	Dropout voltage (1)	I_{OUT}=10mA , V_{IN}=V_{OUTNOM}-0.1V	—	70	—	mV
		I_{OUT}=100mA , V_{IN}=V_{OUTNOM}-0.1V	—	650	—	
	Dropout voltage (1)	I_{OUT}=10mA , V_{IN}=V_{OUTNOM}-0.1V	—	60	—	mV
		I_{OUT}=100mA , V_{IN}=V_{OUTNOM}-0.1V	—	600	—	
$\Delta V_{OUT}/\Delta I_{OUT}$	Load regulation	V_{IN}=7V, 1mA≤I_{OUT}≤100mA	—	0.1	—	mV/mA
$\Delta V_{OUT}/\Delta V_{IN}$	Line regulation	I_{OUT}=1mA, V_{OUTNOM}+0.5V≤V_{IN}≤60V	—	0.1	—	mV/V
I_{LIMIT}	Current limit		—	250	—	mA
T_{SHDN}	Thermal shutdown temperature	Shutdown, temperature increasing	—	150	—	℃
		Reset, temperature decreasing	—	115	—	
PSRR		V_{IN}=10V, I_{OUT}=10mA F=1kHz, VOUT=3.3V	—	70	—	dB

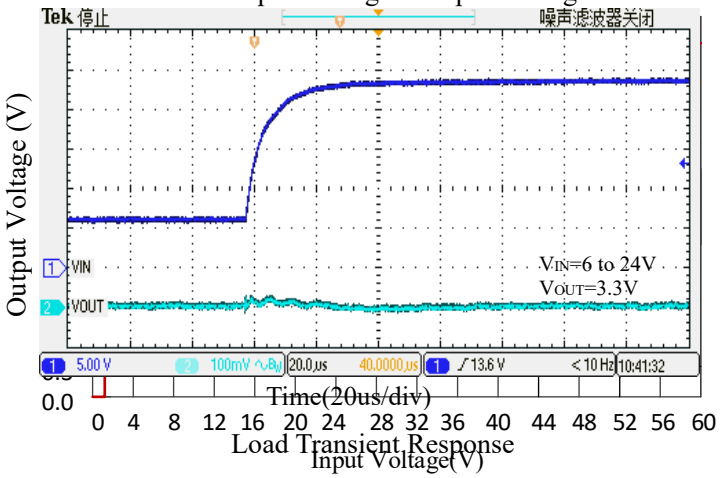
Note:

(1) Dropout Voltage is the voltage difference between the input and the output at which the output voltage drops 2% below its nominal value.

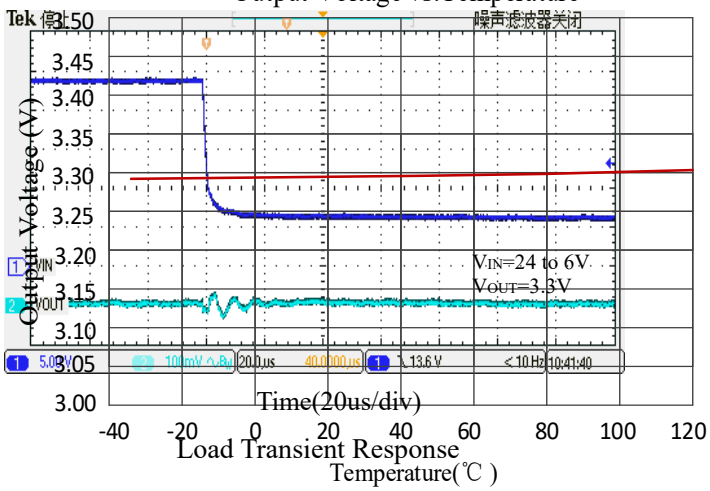
Typical Characteristics

(Test condition: T_A=25℃, V_{IN}=12V, I_{OUT}=1mA, C_{OUT}=10uF, V_{OUT}=3.3V unless otherwise note)

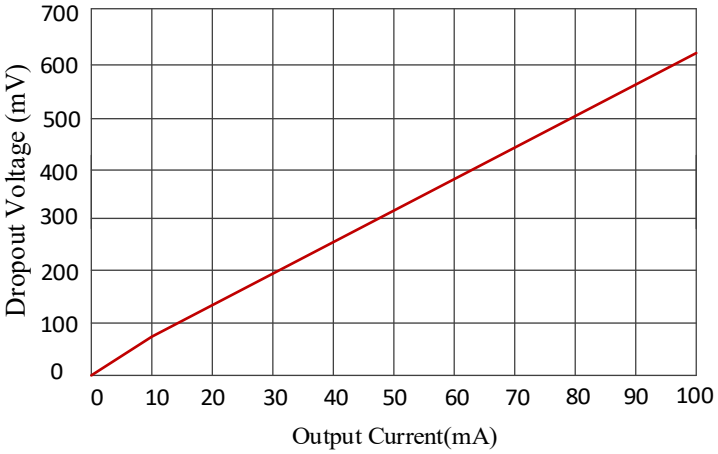
Output Voltage vs.Input Voltage



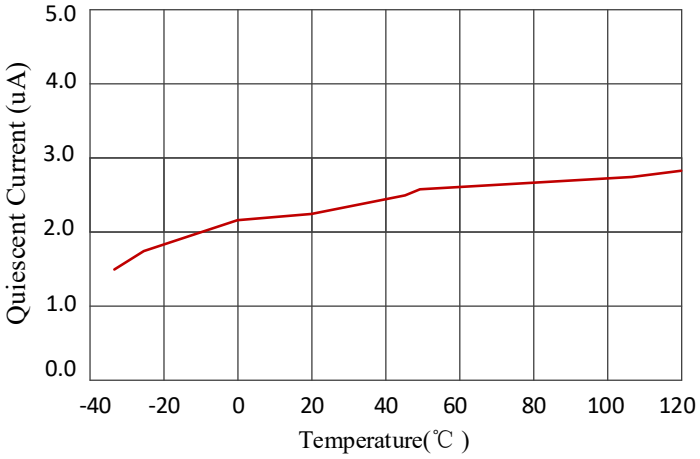
Output Voltage vs.Temperature



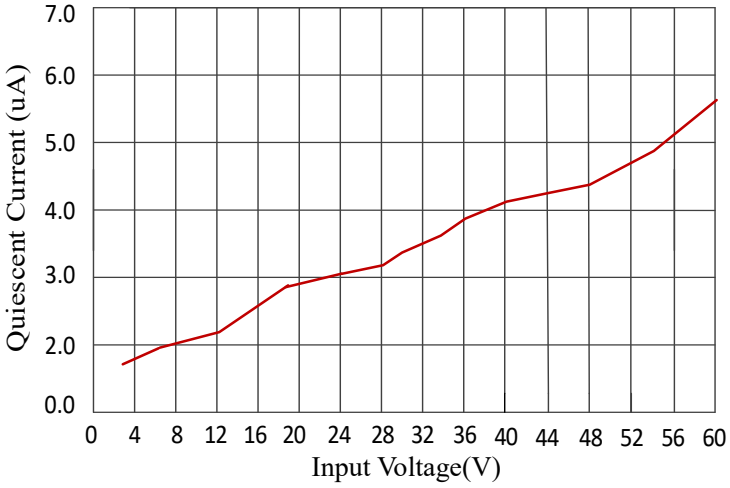
Dropout Voltage vs. Output Current

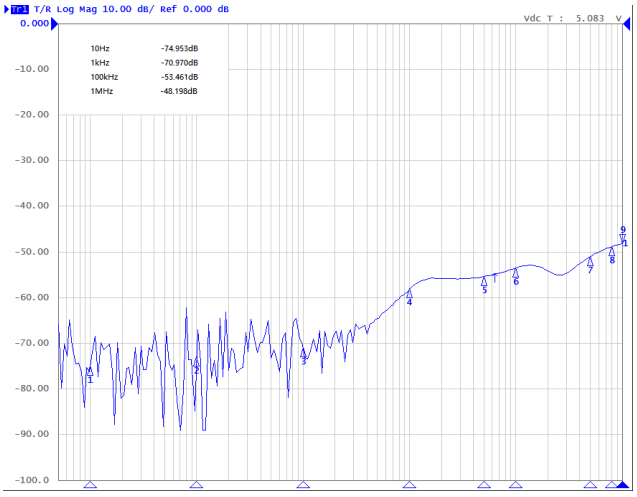


Quiescent Current vs.Temperature



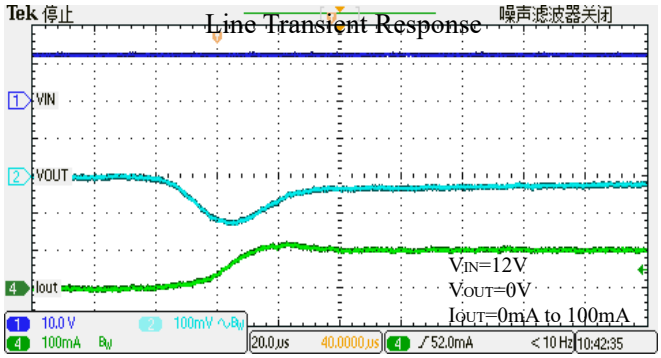
Quiescent Current vs. Input Voltage





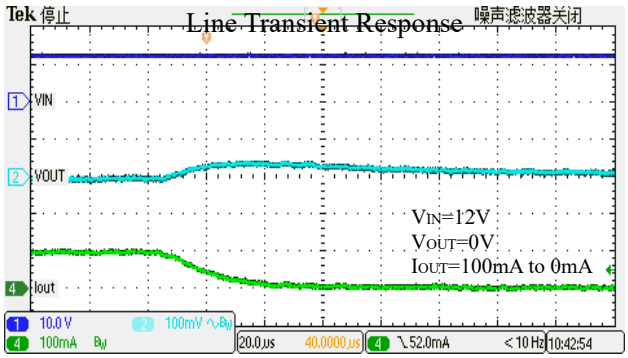
V_{IN}=7V,V_{OUT}=5V,I_{OUT}=10mA

Line Transient Response



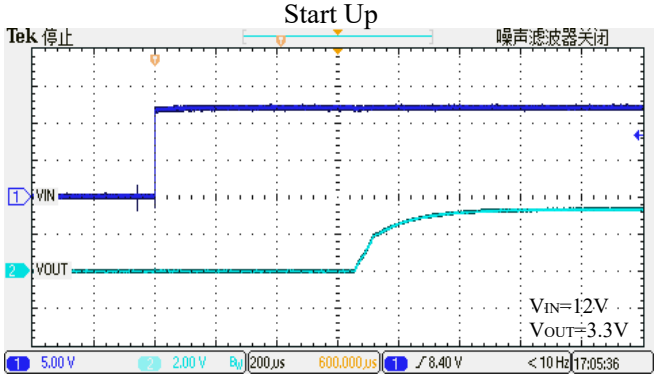
Time(20us /div)

Line Transient Response



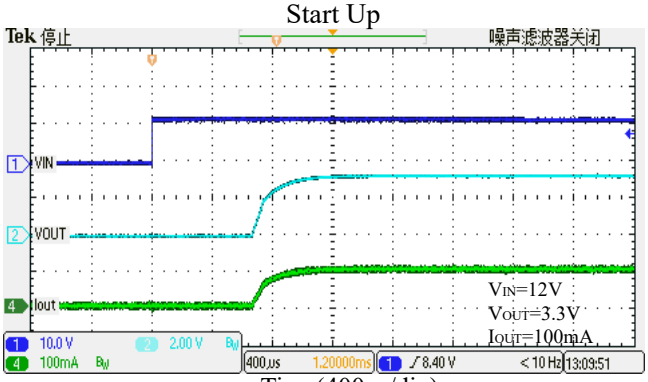
Time(20us/div)

Start Up



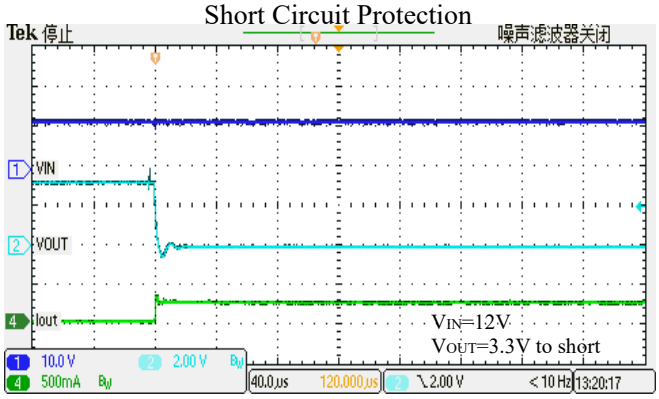
Time(200us/div)

Start Up



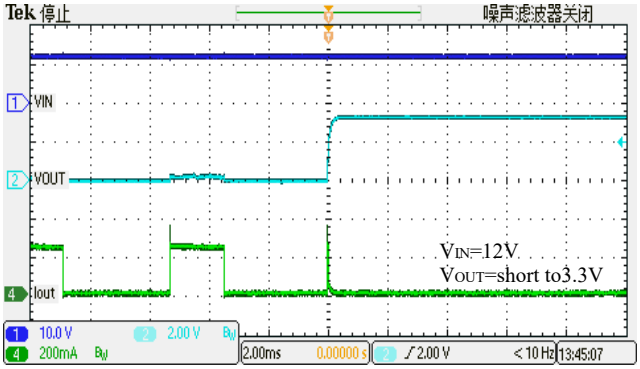
Time(400us/div)

Short Circuit Protection



Time(40us/div)

Short Circuit Protection



Time(2ms/div)

Detailed Description

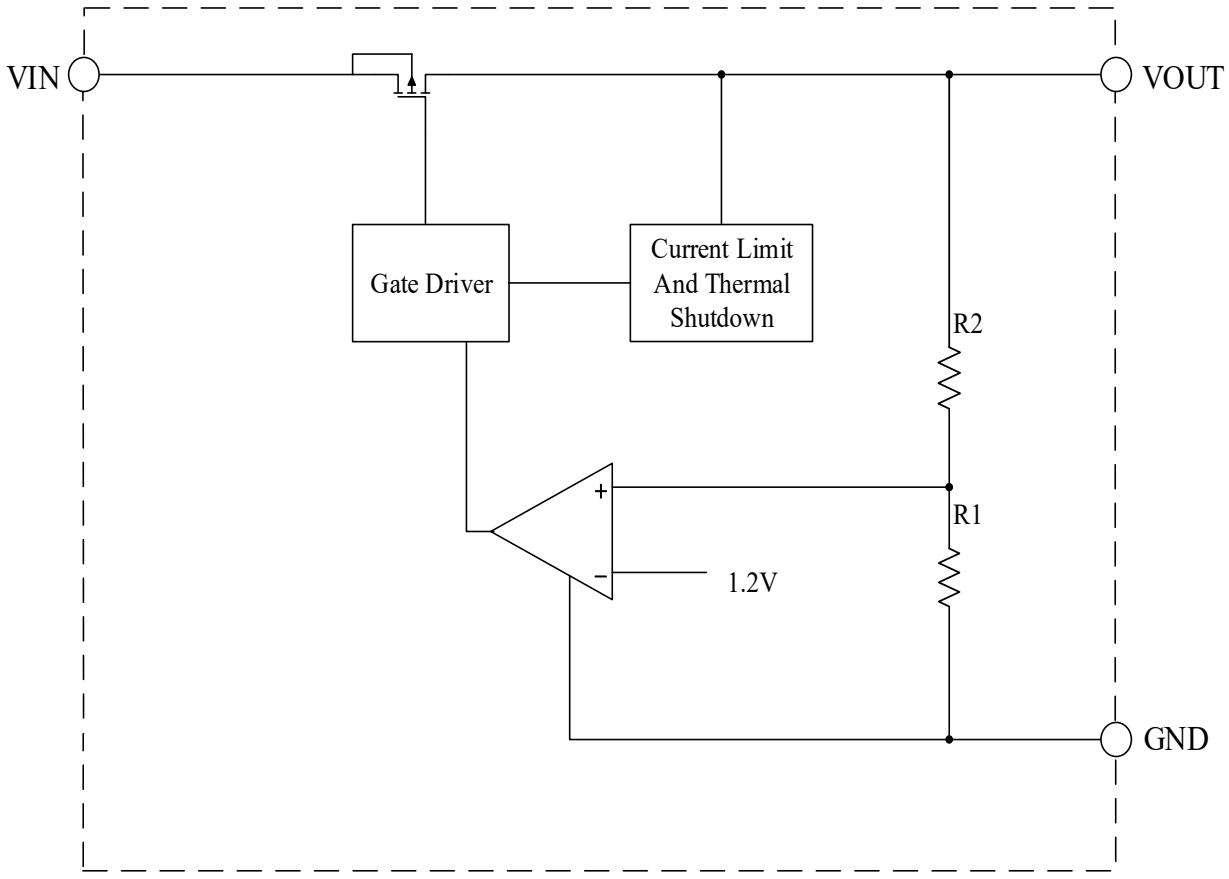
Overview

The OSU26XXA/B series is an ultra-small, low dropout (LDO) linear regulator that can source 150mA of output current. The OSU26XXA/B series is designed to provide high PSRR, high input voltage, and excellent load and line transient performance.

The OSU26XXA/B series has thermal shutdown, current limit, and short Circuit protections for added safety.

The OSU26XXA/B series contains five fixed output voltages of 3.0V, 3.3V, 3.6V, 5.0Vand 12V.

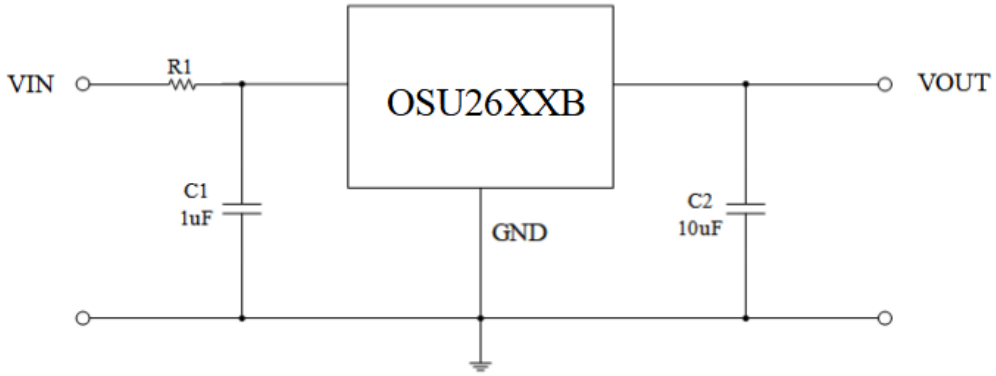
Functional Block Diagram



Functional Block Diagram

Input Capacitor and Output Capacitor

A 1uF ceramic capacitor is recommended to connect between VIN and GND pins to decouple input power supply glitch and noise. The amount of the capacitance may be increased without limit. This input capacitor must be located as close as possible to the device to assure input stability and less noise. For PCB layout, a wide copper trace is required for both VIN and GND. When V_{IN}≥18V, it is recommended to add R1(R1>1Ω, the resistance shall be adjusted according to the actual application) at the input end.



An output capacitor is required for the stability of the LDO. The recommended minimum output capacitance is 10uF, ceramic capacitor is recommended, and temperature characteristics are X5R or X7R. Higher capacitance values help to improve load/line transient response. The output capacitance may be increased to keep low undershoot/overshoot. Place output capacitor as close as possible to VOUT and GND pins.

Current Limit and Short Circuit Protection

When output current at VOUT pin is higher than current limit threshold or the VOUT pin is direct short to GND, the current limit protection will be triggered and clamp the output current at a pre-designed level to prevent over-current and thermal damage.

Power Dissipation and Thermal Protection

The OSU26XXA/B has internal thermal sense and protection circuits. When excessive power dissipation happens on the device, such as short circuit at the output pin or very heavy load current with a large voltage drop across the device, the internal thermal protection circuit will be triggered, and it will shut down the power MOSFET to prevent the LDO from damage. As soon as excessive thermal condition is removed and the temperature of the device drops down, the thermal protection circuit will lease the control of the power MOSFET, and the LDO device goes to normal operation.

Power dissipation caused by voltage drop across the LDO and by the output current flowing through the device needs to be dissipated out from the chip. The maximum junction temperature is dependent on power dissipation, package, the PCB layout, number of used Cu layers, Cu layers thickness and the ambient temperature.

During normal operation, LDO junction temperature should not exceed 150°C, or else it may result in deterioration of the properties of the chip. Using below equations to calculate the power dissipation and estimate the junction temperature.

The power dissipation can be calculated using Equation (1) .

$$P_D = (V_{IN} - V_{OUT}) \times I_{OUT} \quad (1)$$

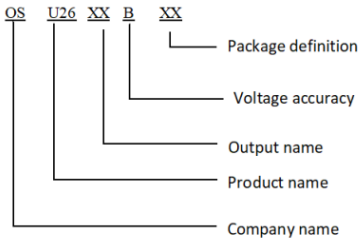
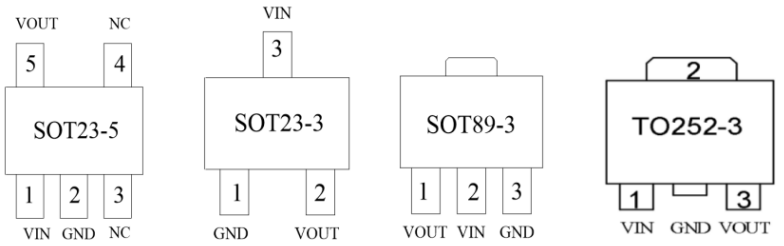
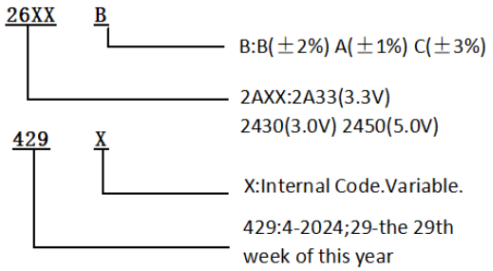
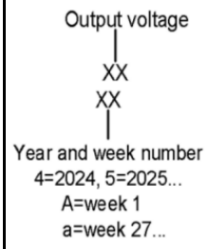
The junction temperature can be estimated using Equation . $R_{\theta JA\_EVM}$ is the junction-to-ambient thermal resistance based on customer's PCB. Verify the application and allow sufficient margins in the thermal design by the Equation (2).

$$T_J = T_A + P_D \times R_{\theta JA\_EVM} \quad (2)$$

$R_{\theta JA\_EVM}$ is a critical parameter and depends on many factors such as the following:

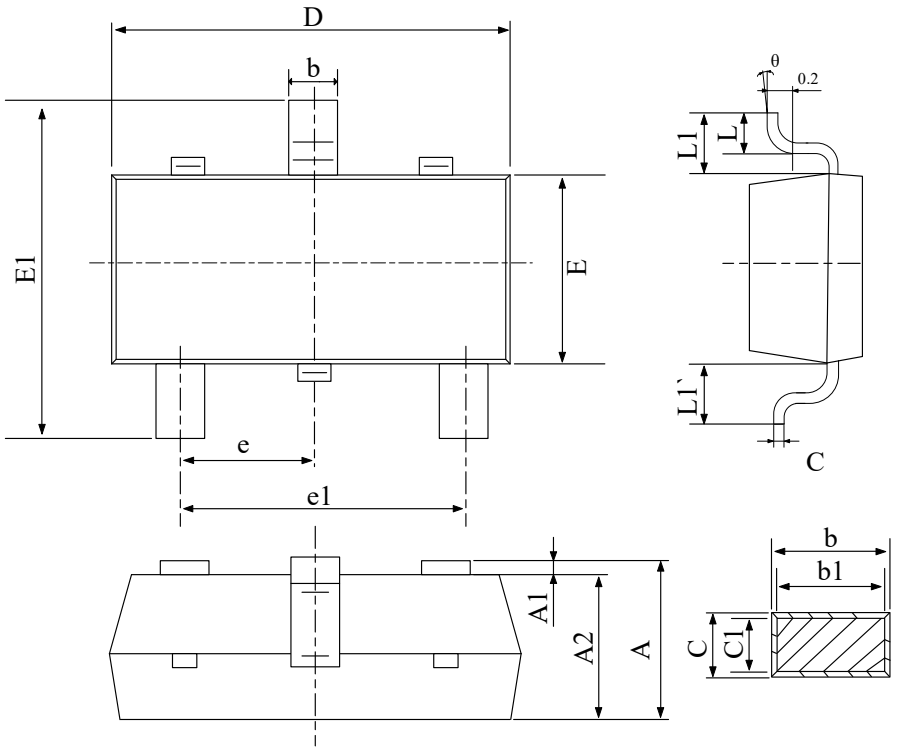
· Power dissipation
· Air temperature/flow
· PCB area
· Copper heat-sink area
· Number of thermal vias under the package
· Adjacent component placement

Ordering And Marking Information

Part Number	Package Outline			
				
Minimum Package	SOT23-5 3000pcs/Reel	SOT23-3 3000pcs/Reel	SOT89-3 1000pcs/Reel	SOT252-3 25000pcs/Reel
Marking				

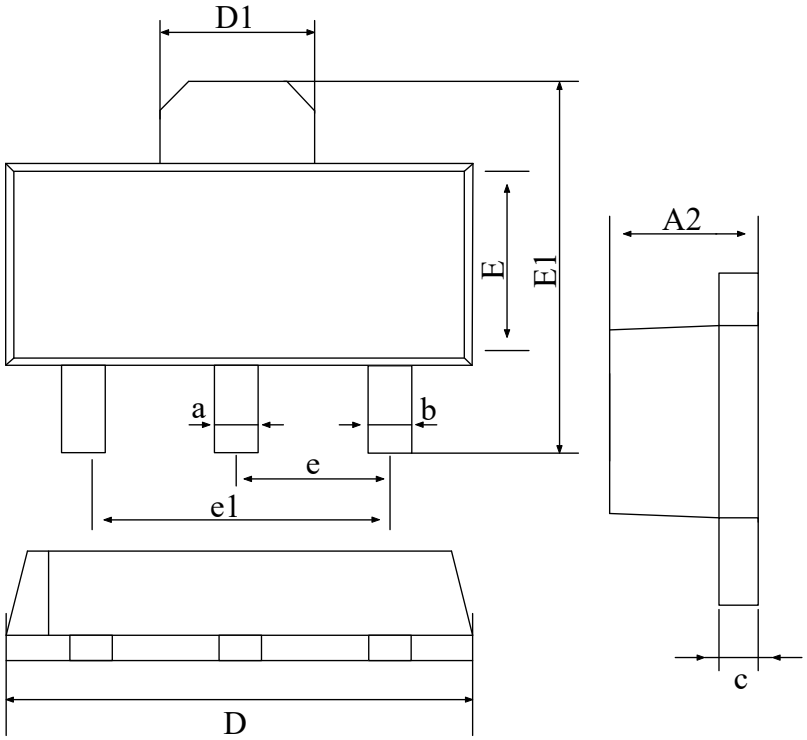
Package Outline

SOT23-3



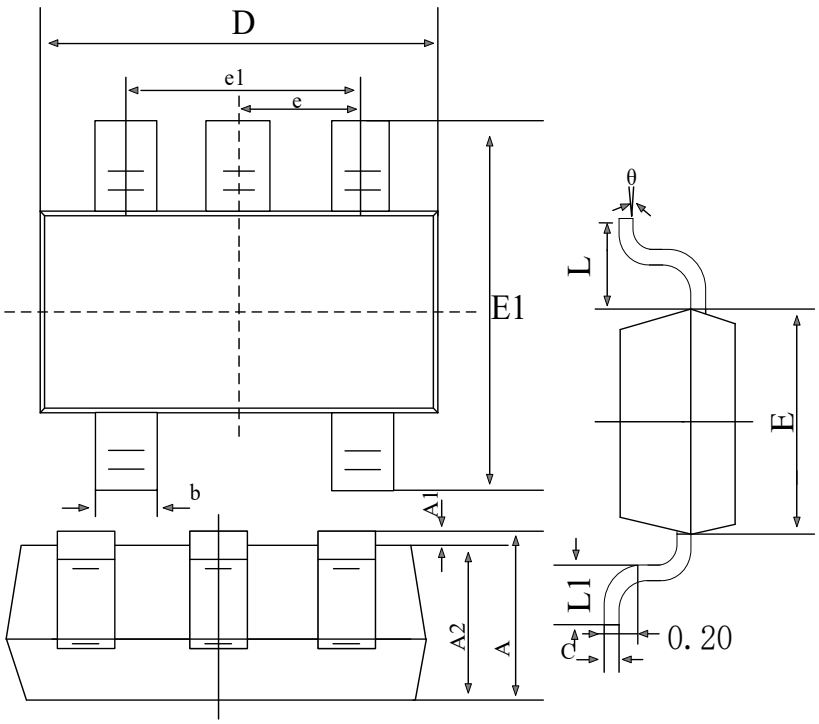
REF	Millimeter	
	Min.	Max.
A	1.05	1.25
A1	0	0.1
A2	1.05	1.15
b	0.30	0.50
b1	0.29	0.47
c	0.10	0.20
c1	0.10	0.18
D	2.85	3.05
E	1.50	1.70
E1	2.65	2.95
e	0.95(BSC)	
e1	1.80	2.00
L	0.30	0.60
L1-L1`	-	0.12
θ	0°	8°

SOT89-3



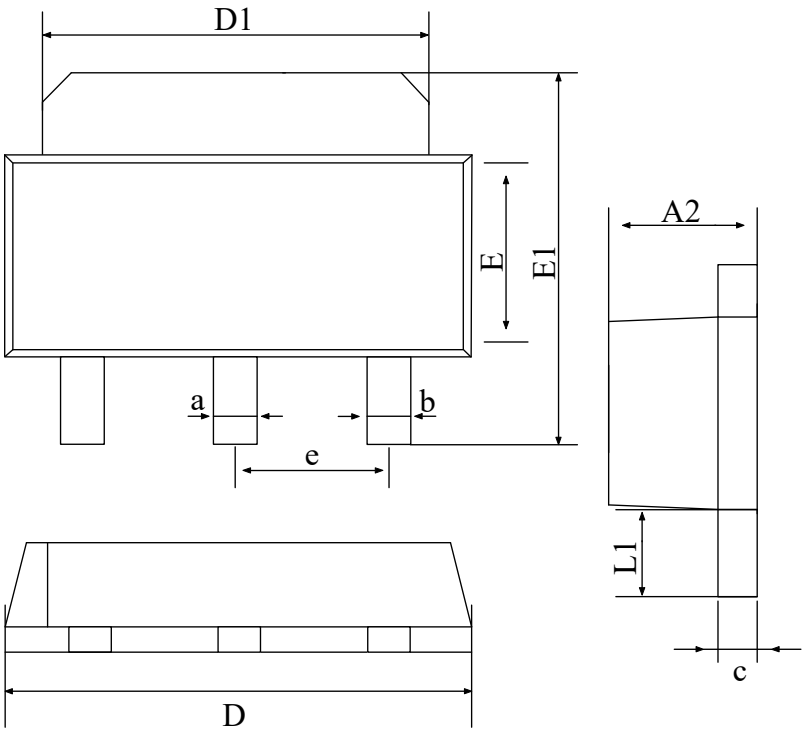
REF.	Millimeter	
	Min.	Max.
A2	1.40	1.60
a	0.40	0.58
b	0.32	0.52
c	0.36	0.46
D	4.40	4.60
D1	1.60	1.80
E	2.30	2.60
E1	4.00	4.30
e	1.00	2.00
e1	2.95	3.05

SOT23-5



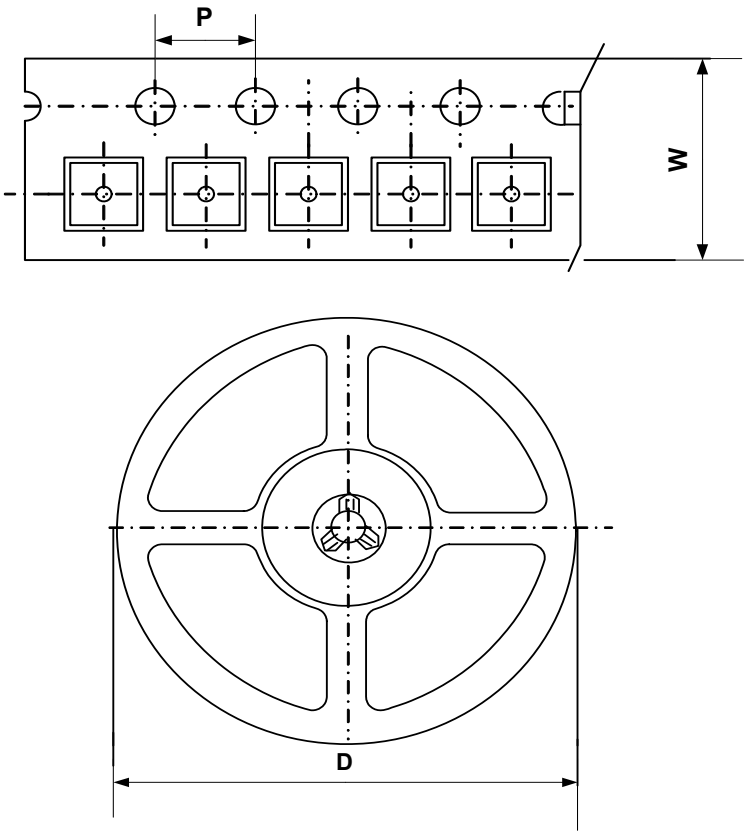
REF	Millimeter	
	Min.	Max.
A	1.05	1.25
A1	0	0.1
A2	1.05	1.15
b	0.3	0.5
c	0.1	0.2
D	2.85	3.05
E	1.5	1.7
E1	2.65	2.95
e	0.95(BSC)	
e1	1.8	2.0
L	0.3	0.6
θ	0°	8°

TO252-3



REF.	Millimeter	
	Min.	Max.
A2	2.20	2.40
a	0.64	0.88
b	0.64	0.88
c	0.45	0.58
D	6.45	6.70
D1	5.10	5.46
E	6.00	6.20
E1	9.40	10.40
e	2.18	2.38
L1	2.90(REF)	

Packing Information



Type	W(mm)	P(mm)	D(mm)	Qty (pcs)
SOT23-3	8.0mm	4.0mm	178.0mm	3000pcs
SOT23-5	8.0mm	4.0mm	178.0mm	3000pcs
SOT89-3	12.0mm	4.0mm	330.0mm	1000pcs
TO252-3	16.0mm	4.0mm	330.0 mm	2500pcs

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